

SNx4AC574 3 ステート出力、オクタル D タイプ・エッジ・トリガ・フリップ・フロップ

1 特長

- 2V~6V の V_{CC} で動作
- 6V までの入力電圧に対応
- 最大 t_{pd} 8.5ns (5V 時)
- 3 ステート出力はバス ラインを直接駆動

2 概要

これらの 8 ビット フリップ フロップ は、大きい容量性負荷または比較的低インピーダンス負荷の駆動用に特化して設計された 3 ステート出力を備えています。本デバイスは、バッファレジスタ、I/O ポート、双方向バスドライバ、作業レジスタの実装に特に適しています。

製品情報

部品番号	パッケージ ⁽¹⁾	パッケージサイズ ⁽²⁾	本体サイズ ⁽³⁾
SNx4AC574	DB (SSOP, 20)	7.2mm × 7.8mm	7.2mm × 5.30mm
	DW (SOIC, 20)	12.8mm × 10.3mm	12.80mm × 7.50mm
	N (PDIP, 20)	24.33mm × 9.4mm	24.33mm × 6.35mm
	PW (TSSOP, 20)	6.5mm × 6.4mm	6.50mm × 4.40mm

- (1) 詳細については、[セクション 10](#) を参照してください。
- (2) パッケージサイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。
- (3) 本体サイズ (長さ × 幅) は公称値であり、ピンは含まれません。

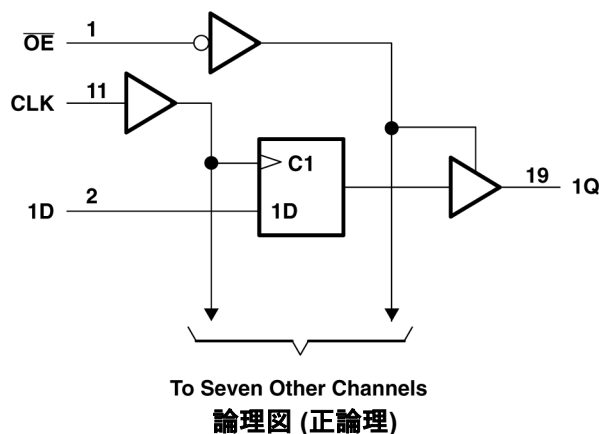


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3 Pin Configuration and Functions

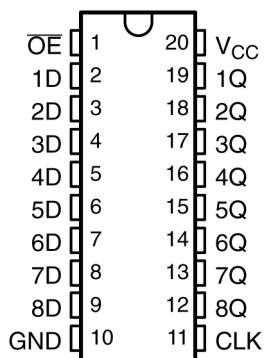


図 3-1. SN54AC574 J or W Package; SN74AC574 DB, DW, N, NS, or PW Package (Top View)

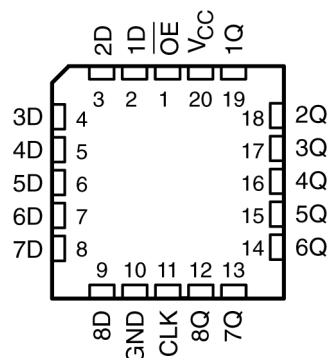


図 3-2. SN54AC574 FK Package (Top View)

表 3-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
OE	1	Input	Output enable for all channels, active low
D1	2	Input	Input for channel 1
D2	3	Input	Input for channel 2
D3	4	Input	Input for channel 3
D4	5	Input	Input for channel 4
D5	6	Input	Input for channel 5
D6	7	Input	Input for channel 6
D7	8	Input	Input for channel 7
D8	9	Input	Input for channel 8
GND	10	—	Ground
CLK	11	Input	Clock input for all channels, rising edge triggered
Q8	12	Output	Output for channel 8
Q7	13	Output	Output for channel 7
Q6	14	Output	Output for channel 6
Q5	15	Output	Output for channel 5
Q4	16	Output	Output for channel 4
Q3	17	Output	Output for channel 3
Q2	18	Output	Output for channel 2
Q1	19	Output	Output for channel 1
V _{CC}	20	—	Positive supply
Thermal Pad		—	The thermal pad can be connect to GND or left floating. Do not connect to any other signal or supply.

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I ⁽²⁾	Input voltage range	-0.5	$V_{CC} + 0.5$	V
V_O ⁽²⁾	Output voltage range	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$(V_I < 0 \text{ or } V_I > V_{CC})$		±20 mA
I_{OK}	Output clamp current	$(V_O < 0 \text{ or } V_O > V_{CC})$		±20 mA
I_O	Continuous output current	$(V_O = 0 \text{ to } V_{CC})$		±50 mA
	Continuous current through V_{CC} or GND			±200 mA
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54AC574		SN74AC574		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2	6	2	6	V
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V}$	2.1	2.1		V
		$V_{CC} = 4.5 \text{ V}$	3.15	3.15		
		$V_{CC} = 5.5 \text{ V}$	3.85	3.85		
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V}$	0.9	0.9		V
		$V_{CC} = 4.5 \text{ V}$	1.35	1.35		
		$V_{CC} = 5.5 \text{ V}$	1.65	1.65		
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 3 \text{ V}$	-12	-12		mA
		$V_{CC} = 4.5 \text{ V}$	-24	-24		
		$V_{CC} = 5.5 \text{ V}$	-24	-24		
I_{OL}	Low-level output current	$V_{CC} = 3 \text{ V}$	12	12		mA
		$V_{CC} = 4.5 \text{ V}$	24	24		
		$V_{CC} = 5.5 \text{ V}$	24	24		
$\Delta t/\Delta v$	Input transition rise or fall rate		8		8	ns/V
T_A	Operating free-air temperature	-55	125	-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.3 Thermal Information

THERMAL METRIC ⁽¹⁾		SNx4AC574					UNIT
		DB (SSOP)	DW (SOIC)	N (PDIP)	NS (SOP)	PW (TSSOP)	
		20 PINS					
R _{θJA}	Junction-to-ambient thermal resistance	70	101.2	69	60	126.2	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.46		
		4.5 V	3.94			3.7		3.76		
		5.5 V	4.94			4.7		4.76		
V _{OL}	I _{OL} = 50 μA	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.5		0.44	
		4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
I _I	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.5		±5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4		80		40	μA
C _i	V _I = V _{CC} or GND	5 V			4.5					pF

4.5 Timing Requirements, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

		T _A = 25°C		SN54AC574		SN74AC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		75		55		60	MHz
t _w	Pulse duration, CLK high or low	6		7.5		7		ns
t _{su}	Setup time, data before CLK ↑	2.5		6.5		3		ns
t _h	Hold time, data after CLK ↑	1.5		2.5		1.5		ns

4.6 Timing Requirements, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

		$T_A = 25^\circ\text{C}$		SN54AC574		SN74AC574		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	95		85		85		MHz
t_w	Pulse duration, CLK high or low	4		5		5		ns
t_{su}	Setup time, data before CLK $\uparrow$	1.5		3.5		2		ns
t_h	Hold time, data after CLK $\uparrow$	1.5		2.5		1.5		ns

4.7 Switching Characteristics, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			75	112		55		60		MHz
t_{PLH}	CLK	Q	3.5	8.5	13.5	1	16.5	3.5	15	ns
t_{PHL}			3.5	7.5	12	1	15	3.5	13.5	
t_{PZH}	$\overline{\text{OE}}$	Q	2.5	7	11	1	13	2.5	12	ns
t_{PZL}			3	6.5	10.5	1	12.5	3	11.5	
t_{PHZ}	$\overline{\text{OE}}$	Q	3.5	7.5	12	1	14	2.5	13	ns
t_{PLZ}			2	5.5	9	1	10.5	1.5	10	

4.8 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

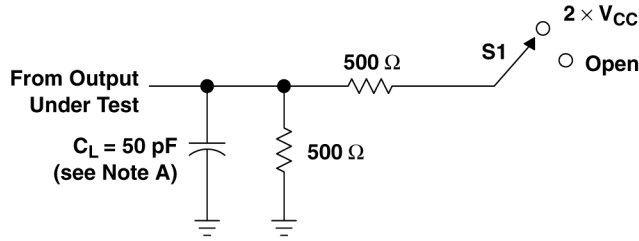
PARAMETER	TO (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC574		SN74AC574		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			95	153		85		85		MHz
t_{PLH}	CLK	Q	2	6	9.5	1.5	11.5	2	11	ns
t_{PHL}			2	5.5	8.5	1.5	10.5	2	9.5	
t_{PZH}	$\overline{\text{OE}}$	Q	2	5	8.5	1.5	9.5	2	9	ns
t_{PZL}			2	5	8	1.5	9.5	1.5	9	
t_{PHZ}	$\overline{\text{OE}}$	Q	2	6	9.5	1.5	11.5	1.5	10.5	ns
t_{PLZ}			1	4.5	7.5	1.5	9	1	8.5	

4.9 Operating Characteristics

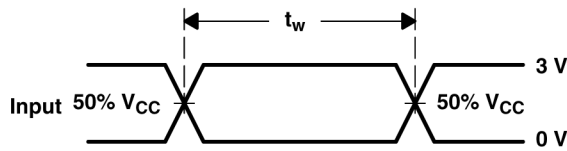
$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$		40	pF

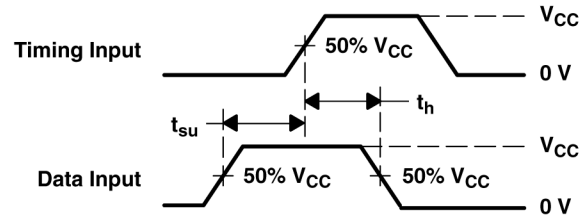
5 Parameter Measurement Information



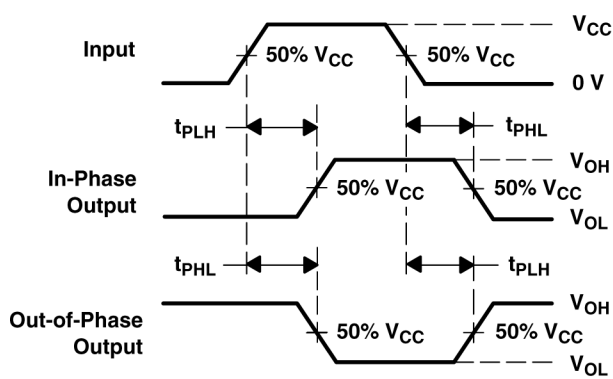
LOAD CIRCUIT



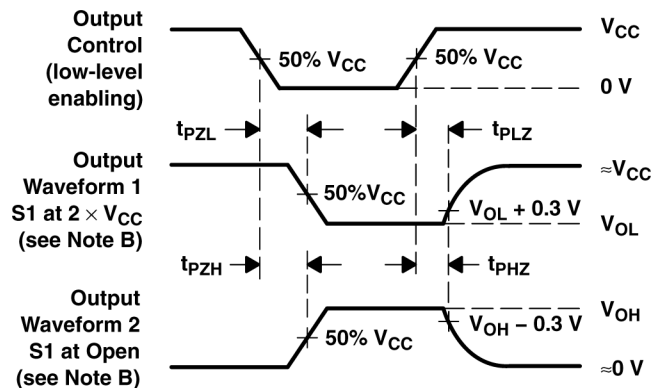
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

图 5-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	Open

6 Detailed Description

6.1 Overview

The eight flip-flops of the 'AC574 devices are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

For the specified high-impedance state during power up or power down, $\overline{OE}$ must be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

6.2 Functional Block Diagram

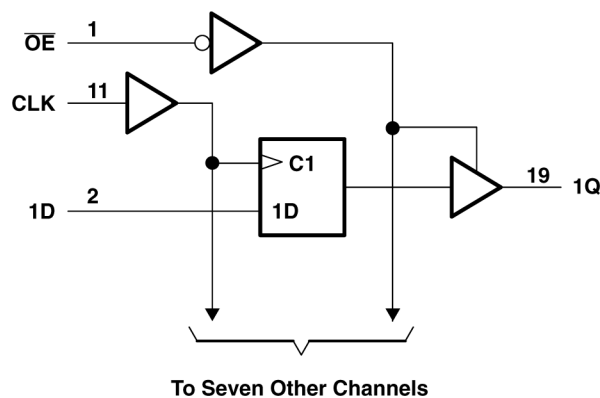


図 6-1. Logic Diagram (Positive Logic)

6.3 Device Functional Modes

表 6-1. Function Table (Each Flip-flop)

INPUTS			OUTPUT Q
$\overline{OE}$	CLK	D	
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	Q_0
H	X	X	Z

7 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

7.1 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the Recommended Operating Conditions table.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1 μF capacitor is recommended. If there are multiple V_{CC} terminals then 0.01 μF or 0.022 μF capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1 μF and 1.0 μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for the best results.

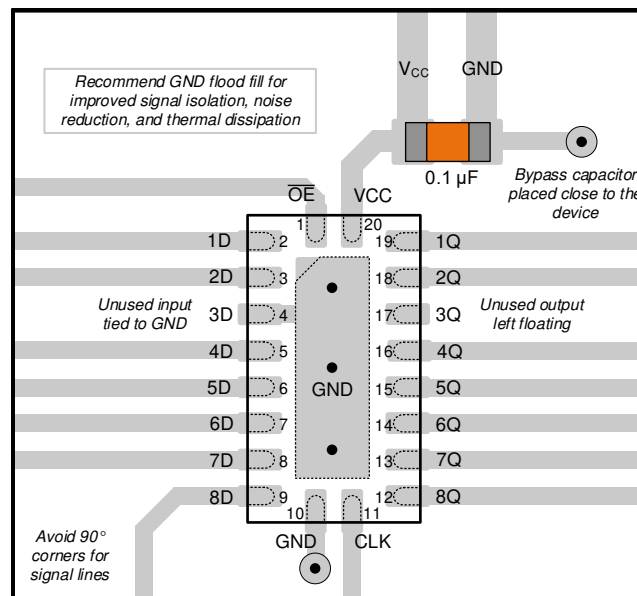
7.2 Layout

7.2.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [layout example](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

7.2.1.1 Layout Example



7-1. Layout example for the SNx4AC574

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and Cpd Calculation application report](#)
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application report](#)

8.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

8.3 サポート・リソース

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8.4 Trademarks

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8.5 静電気放電に関する注意事項



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ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

8.6 用語集

[テキサス・インスツルメンツ用語集](#)

この用語集には、用語や略語の一覧および定義が記載されています。

9 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision F (August 2023) to Revision G (March 2024)	Page
• Updated RθJA values: DW = 58 to 101.2, PW = 83 to 126.2, all values in °C/W	5
• Added <i>Application and Implementation</i> section.....	9

Changes from Revision E (October 2003) to Revision F (August 2023)	Page
• 「製品情報」表、「ピンの機能」表、「熱に関する情報」表、「デバイスの機能モード」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加.....	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9677301Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9677301Q2A SNJ54AC 574FK	Samples
5962-9677301QRA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677301QR A SNJ54AC574J	Samples
5962-9677301QSA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677301QS A SNJ54AC574W	Samples
SN74AC574DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC574	Samples
SN74AC574DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC574	Samples
SN74AC574N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC574N	Samples
SN74AC574PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC574	Samples
SN74AC574PWRG4	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC574	Samples
SNJ54AC574FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9677301Q2A SNJ54AC 574FK	Samples
SNJ54AC574J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677301QR A SNJ54AC574J	Samples
SNJ54AC574W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9677301QS A SNJ54AC574W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AC574, SN74AC574 :

- Catalog : [SN74AC574](#)
- Military : [SN54AC574](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC574DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC574DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AC574DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AC574PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AC574PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC574DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74AC574DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC574DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AC574PWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74AC574PWR	TSSOP	PW	20	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9677301Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9677301QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74AC574N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54AC574FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC574W	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

NOTES:

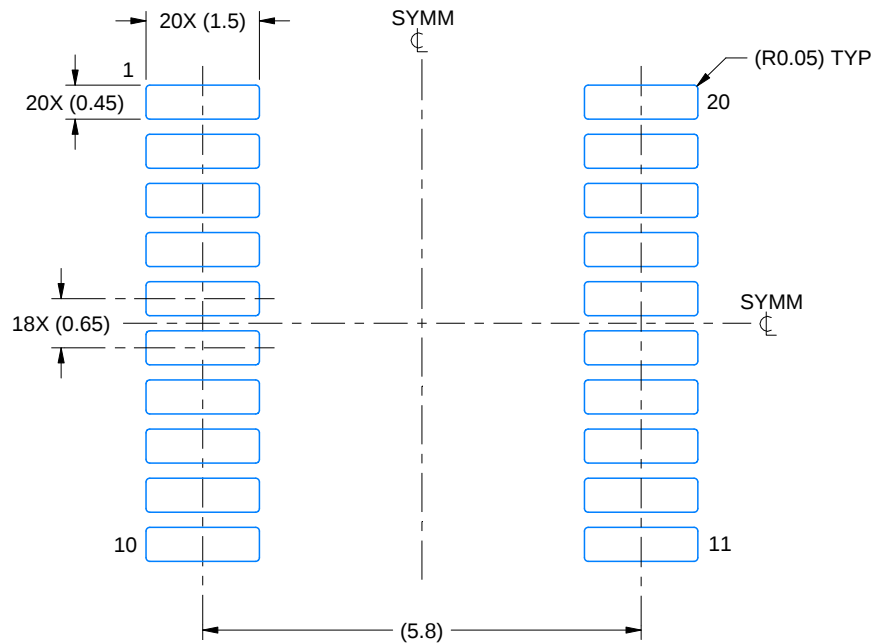
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

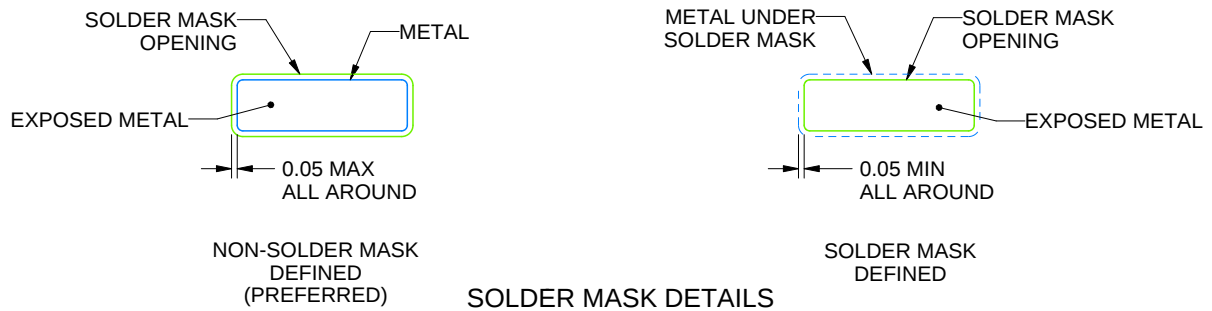
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

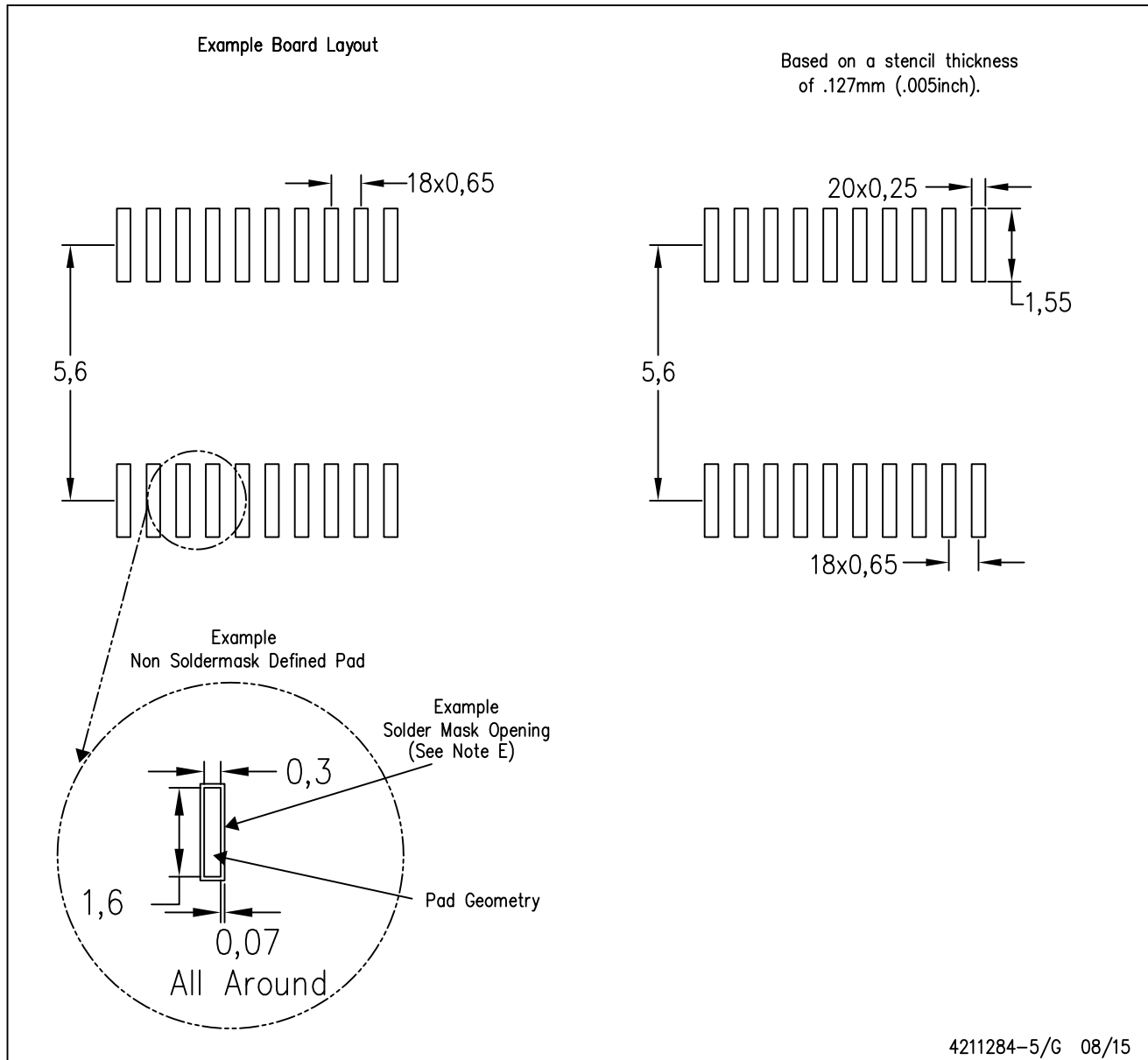
4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



4214851/B 08/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

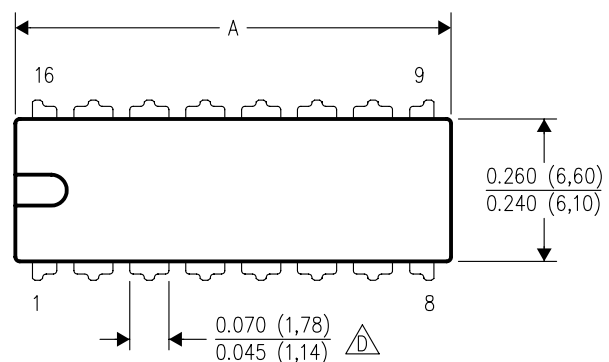


4229370VA\

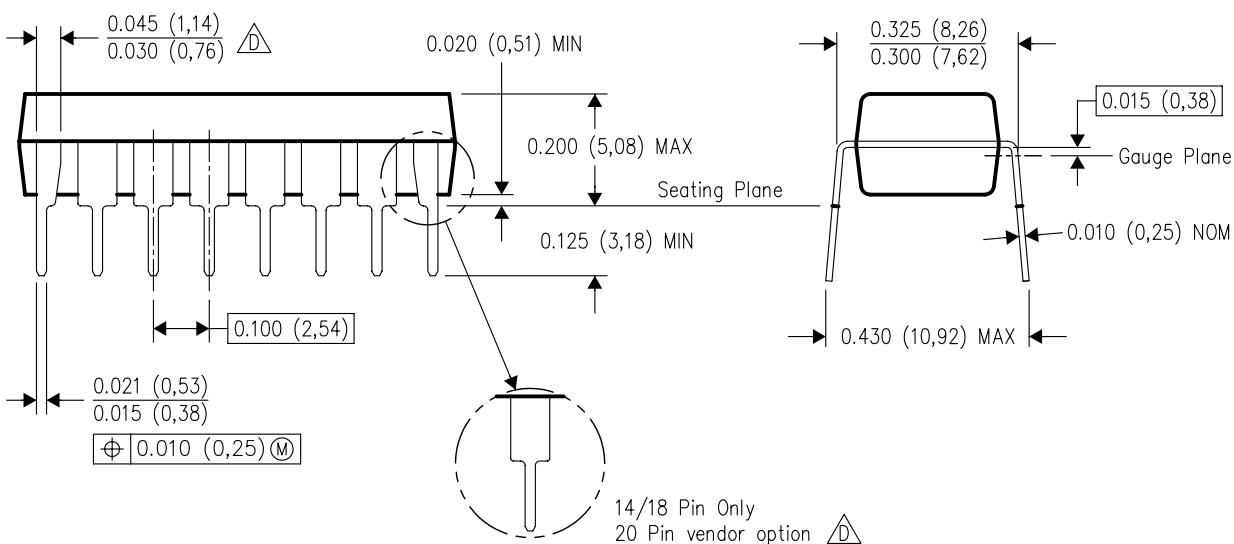
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE

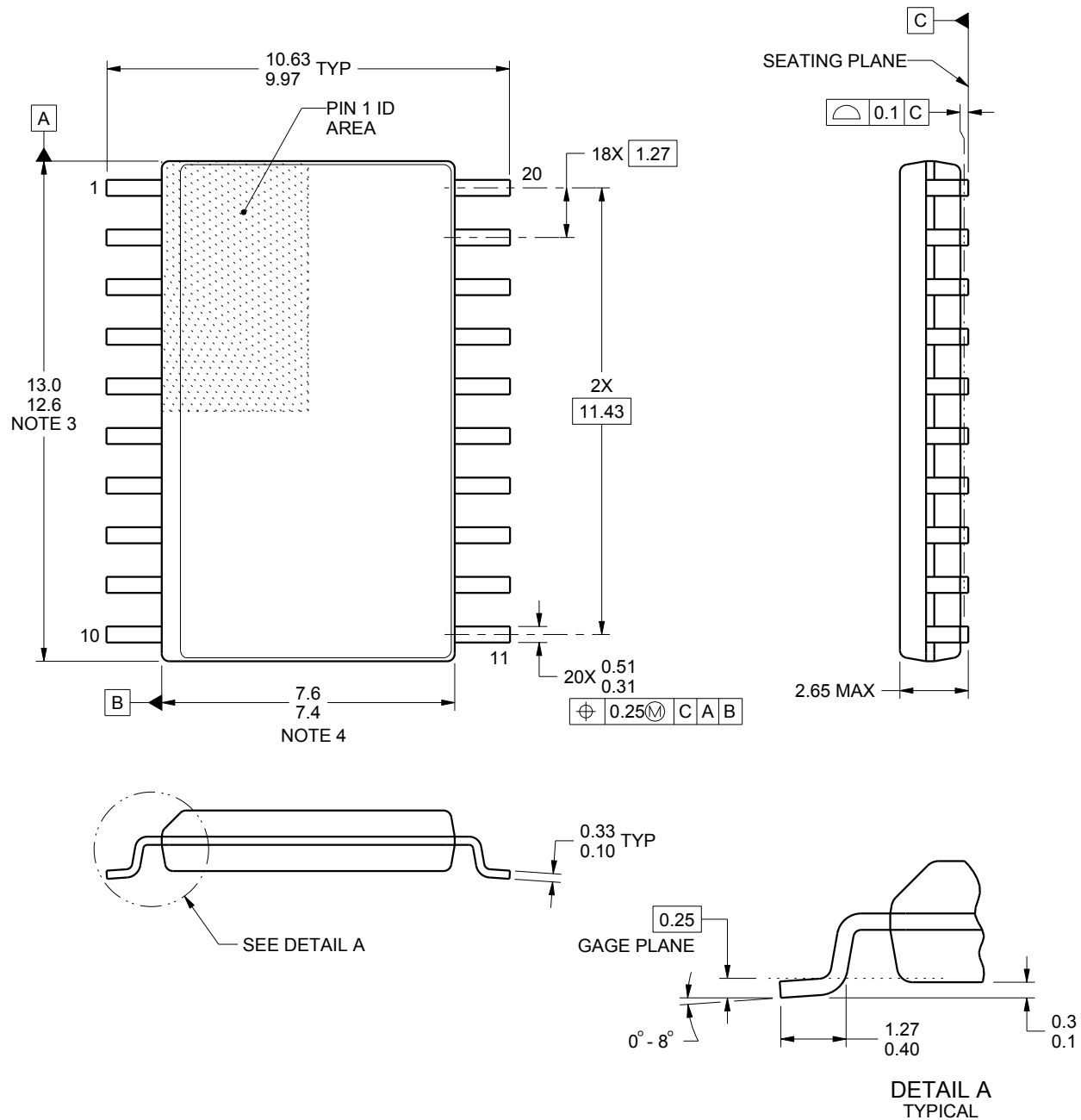
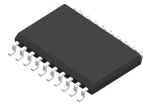


PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

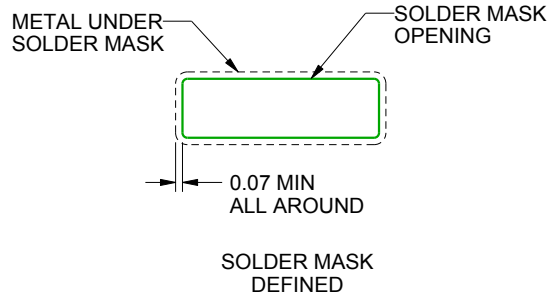
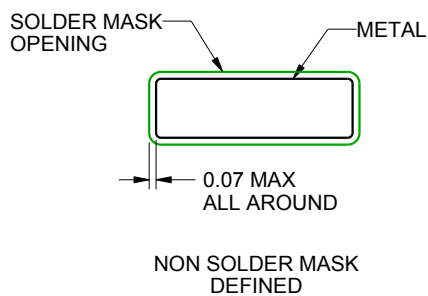
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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